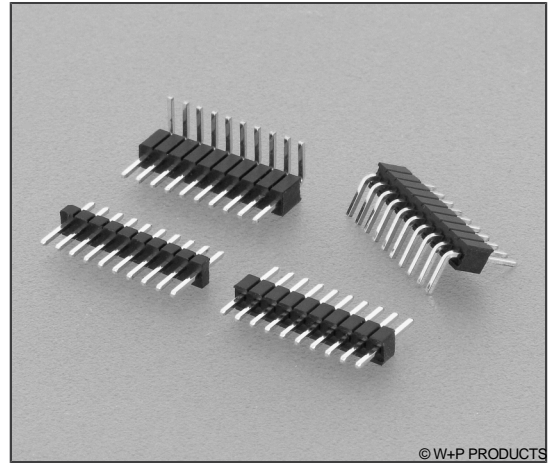


46-707 Economy Version

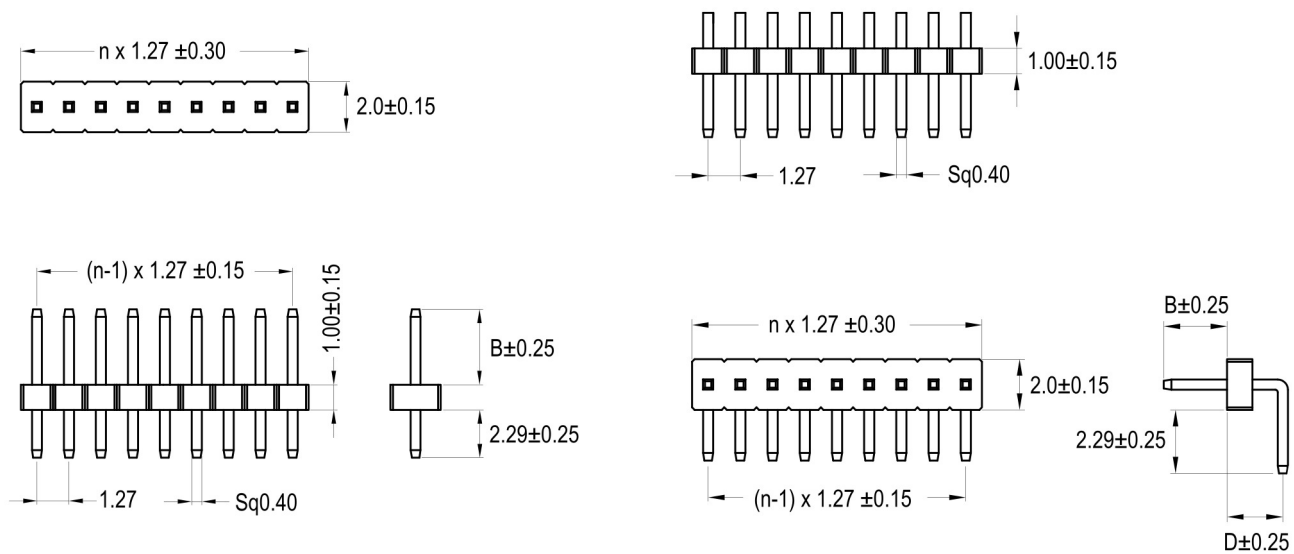
Stiftleisten RM 1,27mm, gerade/gewinkelt, 1-reihig – 1,0-2,5mm Isolierkörper
 Pin Headers, 1.27mm Pitch, Straight/Right-Angled, Single Row – 1.0-2.5mm Body

Technische Daten / Technical Data

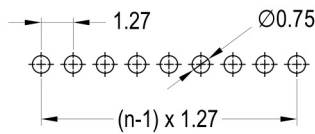
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Au über Ni
Contact Surface	Au over Ni
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	> 1000 MΩ
Spannungsfestigkeit	500 V AC
Test Voltage	500 V AC
Nennstrom	1 A
Current Rating	1 A
Temperaturbereich	-40 °C ~ +105 °C
Temperature Range	-40 °C ~ +105 °C
Verarbeitung	260 °C für 10 sec. / 230 °C für 30-60 sec.
Processing	260 °C for 10 sec. / 230 °C for 30-60 sec.



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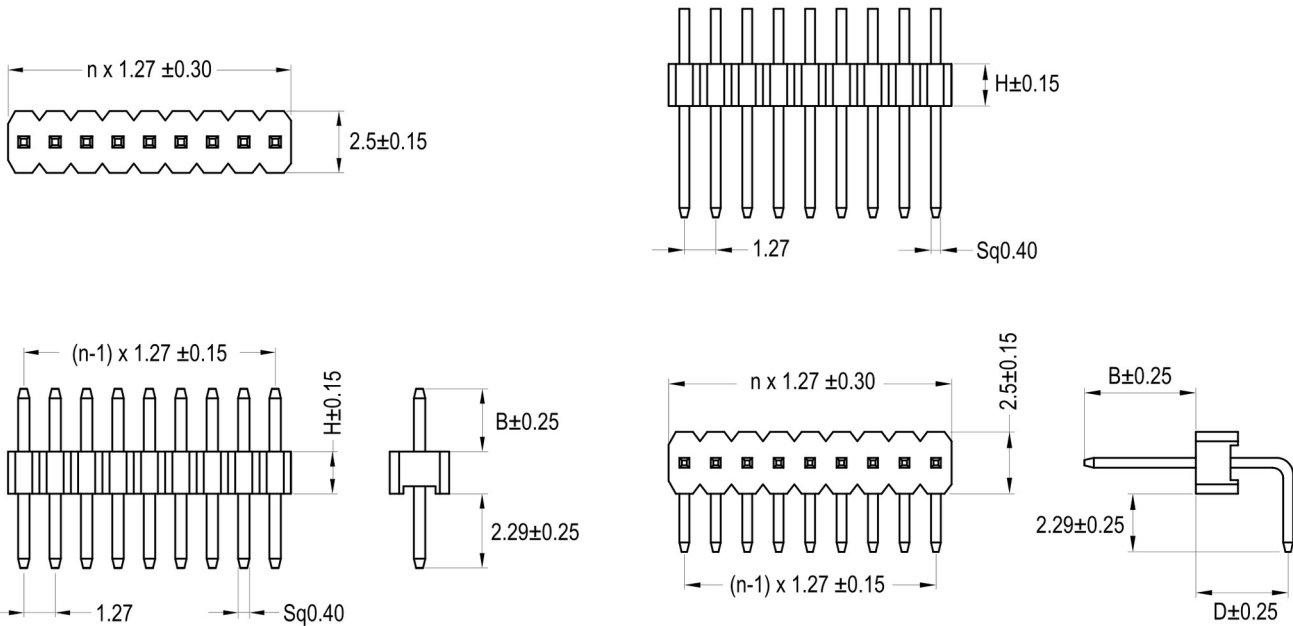
Recommended PCB Layout (PCB Board Tolerance ± 0.05)



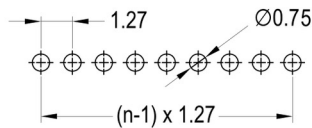
Series	Height	Contacts*	Type*	Dimensions*	Plating
46-707	1 1 H=1.0mm	09 02-40	1 1 Gerade Straight 2 Gewinkelt Right-angled	30 10 B=2.70mm (D=1.50mm) 20 B=3.05mm (D=1.50mm) 30 B=1.91mm (D=2.20mm) 40 B=1.65mm (D=2.20mm) 50 B=1.91mm (D=2.80mm) 60 B=3.05mm (D=2.80mm) 99 Kundenspezifisch Customer-specific	00 00 Vergoldet Gold plated

46-707 Economy Version

Stiftleisten RM 1,27mm, gerade/gewinkelt, 1-reihig – 1,0-2,5mm Isolierkörper
 Pin Headers, 1.27mm Pitch, Straight/Right-Angled, Single Row – 1.0-2.5mm Body



Recommended PCB Layout
 (PCB Board Tolerance ± 0.05)



Series	Height*	Contacts*	Type*	Dimensions*	Plating
46-707	2	09	1	30	00
	2 H=1.5mm 3 H=1.7mm 4 H=2.5mm	02-40 Type 2, 4 02-30 Type 3	1 Gerade Straight 2 Gewinkelt Right-angled	10 B=2.70mm (D=1.50mm) 20 B=3.05mm (D=1.50mm) 30 B=1.91mm (D=2.20mm) 40 B=1.65mm (D=2.20mm) 50 B=1.91mm (D=2.80mm) 60 B=3.05mm (D=2.80mm) 99 Kundenspezifisch Customer-specific	00 Vergoldet Gold plated

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** - please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

